

D&X

Co., Ltd.

Corporate Profile & Catalog

Your Partner in Semiconductor Innovation



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ABOUT US

Your Partner in Semiconductor Innovation.





Welcome to D&X: Your Partner in Semiconductor Innovation

Since our founding in 2008, D&X has been a trusted name in the semiconductor industry, driving innovation in manufacturing and materials trading. We specialize in the R&D, production and sales of essential semiconductor materials such as silicon wafers and semiconductor tape, and provide a full range of wafer processing services including dicing, bonding, grinding, and film deposition. Guided by our commitment to high quality and fast delivery, we've remained at the forefront of the industry for over a decade. Our dedicated team continues to meet the evolving needs of our customers, building strong, lasting partnerships around the globe. We are deeply grateful for your continued support and trust. As we look ahead, we're excited to work together to shape the future of semiconductor technology.



16+

Years of experience in the industry

500+

Number of customers worldwide

1000+

Number of inventory categories

100+

Number of employees

Company Profile

Company Name: D&X Co., Ltd.

Established: April, 2008

Headquarters: 1-1-4. Nagaoka, Mizuho, Nishitama-Gun, Tokyo, 190-1232, Japan

Headquarters Area: 1,241 m²

Branch Office: Taiwan - Taipei

Germany - Duisburg

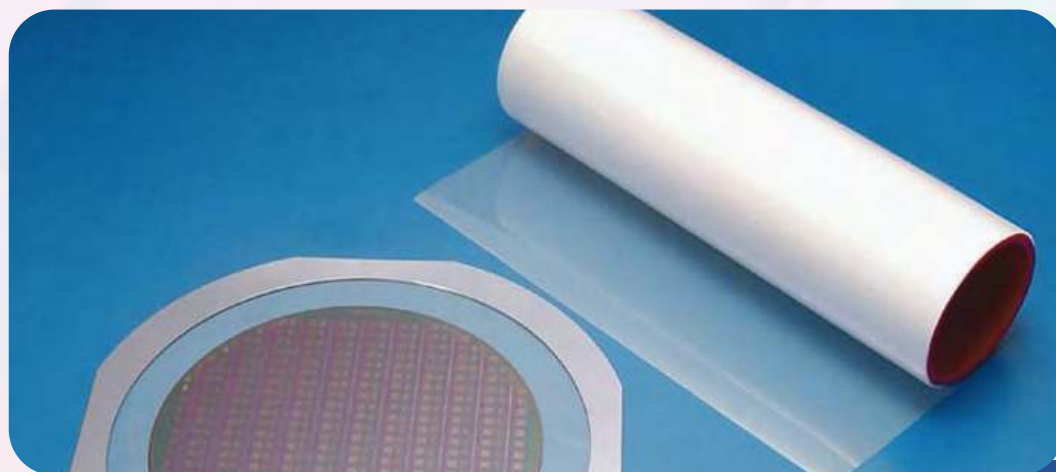
China - Shanghai

President: Hiiragi Hajime

Number of Employees: 100+



PRODUCTS & SERVICES



Back-Grinding Tape
Dicing Tape
Bump Tape

TAPE



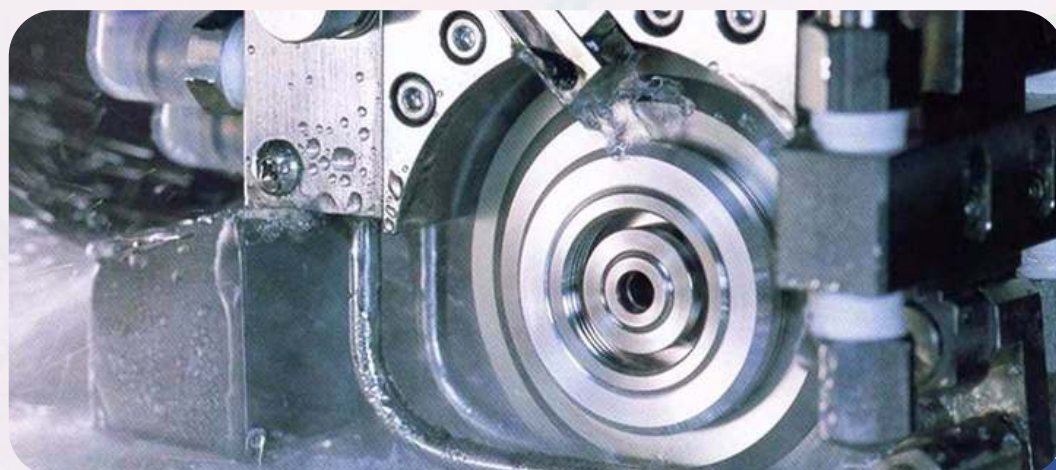
Silicon Wafers (Various Grades)
Film Coated Wafers
Special Material Wafers
Specialized Wafers

WAFERS



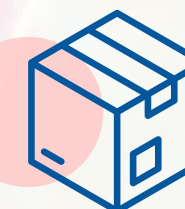
Cassettes
Wafer Rings

ACCESSORIES



Wafer Surface Preparation
Film Deposition & Bonding
Wafer Dicing & Patterning
Wafer Assembly, Packaging & Cleaning

PROCESSING



SWIFT DELIVERY



LOW MOQ



HIGH QUALITY



TAPE

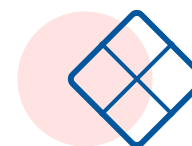
Your One-Stop Provider for Tape Solutions at Every Step

Our **Japan-made** tapes are engineered for the high demands of semiconductor manufacturing, offering **consistent performance** and **specialized features** you can rely on. Contact us to discuss samples.



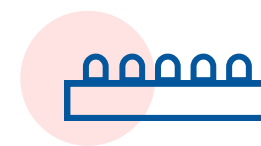
Back-Grinding Tape

- Available in UV and Non-UV types
- Strong adhesion prevents wafer damage
- No adhesive residue left behind
- Ultra-flat surface for optimal grinding
- Works well on uneven surfaces as well



Dicing Tape

- Available in UV and Non-UV types
- Uniform expansion for precise separation
- Reduces chipping and prevents whiskers
- Strong adhesive properties
- High heat resistance



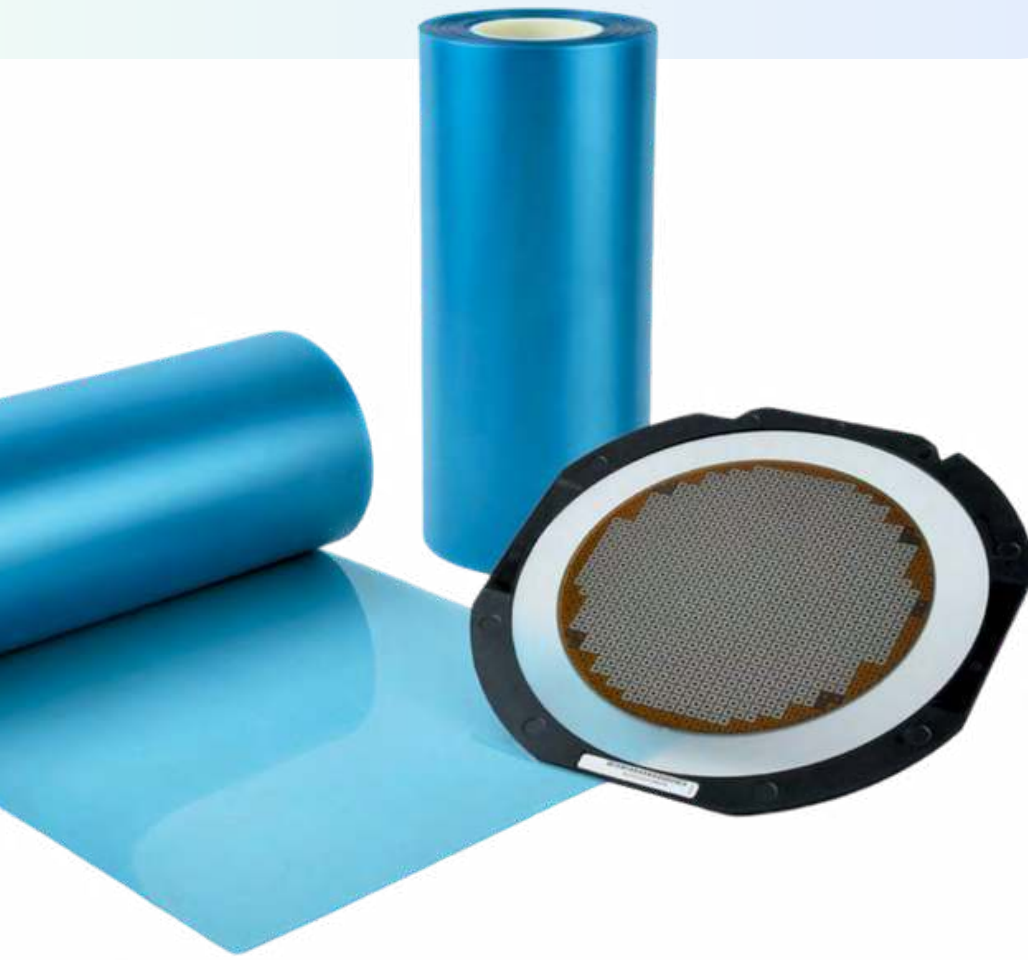
Bump Tape

- Supports various bump sizes, heights, and distances
- No adhesive residue or damage to bumps
- Heat and long-term film protection
- Suitable for back-grinding

*For more details, please refer to our tape list on the following pages.

WE OFFER

- **Customizable:** Width, length, thickness, hardness, viscosity, and adhesion
- **Short Lead-time:** Ships quickly via FedEx, DHL, UPS, or other domestic forwarders
- **Flexible quantities:** From short rolls to full production runs
- **Easy terms:** Negotiable payment and shipping options
- **Certified quality:** Inspection sheet included with every shipment



Dicing Tape List [1/2]

Item Name	Use	UV Type	Thickness (μm)	Base Material (μm)	Adhesive (μm)	Adhesive Strength (Before UV) mN/25mm	Adhesive Strength (After UV) mN/25mm	Color	Properties
DX-TAB180C-A	Packaging substrates	UV	180	EVA150	Acrylic 30	14000	140	Blue (Translucent)	Prevents chipping, Good chip peeling by hand
DX-TAD85C-R-X	Silicon Wafer	UV	85	PVC70	Acrylic 15	6500	260	Colorless (Translucent)	Prevents chipping, Supports small chips
DX-TAD95C	Silicon Wafer	UV	95	PVC80	Acrylic 15	2500	100	Colorless (Transparent)	Transparent, Highly expandable
DX-TAD95C-R	Silicon Wafer	UV	95	PVC80	Acrylic 15	3100	180	Colorless (Transparent)	Transparent, Highly expandable RoHS2.0 compliant
DX-TAD95C-AS	Silicon Wafer	UV	95	PVC80	Acrylic 15	2900	150	Colorless (Transparent)	Transparent, Highly expandable RoHS2.0 compliant Antistatic
DX-TAU75	Glass, Ceramics	UV	75	PET50	Acrylic 25	23000	100	Colorless (Transparent)	
DX-TAU115	Glass, Ceramics	UV	115	PET100	Acrylic 15	19000	100	Colorless (Transparent)	
DX-TAU125B	Packaging substrates, hard to cut surfaces	UV	125	PET100	Acrylic 25	30000	150	Colorless (Transparent)	Strong adhesive
DX-TAU213F	Packaging substrates, hard to cut surfaces	UV	213	PET188	Acrylic 25	40000	170	Colorless (Transparent)	Strong adhesive
DX-TAP100	Packaging Substrates, Glass	UV	100	PO90	Acrylic 10	5800	180	Frosted (Translucent)	
DX-TAP110	Packaging Substrates, Glass	UV	110	PO100	Acrylic 10	11600	110	Colorless (Translucent)	
DX-TAP115P	Packaging Substrates, Glass	UV	115	PO100	Acrylic 15	21900	180	Colorless (Transparent)	

Dicing Tape List [2/2]

Item Name	Use	UV Type	Thickness (μm)	Base Material (μm)	Adhesive (μm)	Adhesive Strength (Before UV) mN/25mm	Adhesive Strength (After UV) mN/25mm	Color	Properties
DX-M14P10S	Packaging substrates	UV	150	PO140	Acrylic 10	8250	200	Colorless (Transparent)	Strong adhesive, Prevents chipping
DX-TAP155D	Packaging substrates	UV	155	PO140	Acrylic 15	34800	190	Colorless (Translucent)	Strong adhesive, Prevents chipping
DX-TAP165EZ	Packaging substrates	UV	165	PO150	Acrylic 15	24900	160	Colorless (Translucent)	Strong adhesive, Prevents chipping
DX-TAP165E-AS	Packaging substrates	UV	165	PO150	Acrylic 15	18000	160	Colorless (Transparent)	Strong adhesive, Prevents chipping, Antistatic
DX-TAP165	Packaging Substrates, Glass	UV	165	PO150	Acrylic 15	19000	180	Frosted (Translucent)	
DX-TAP175	Packaging Substrates, Glass	UV	175	PO150	Acrylic 25	21000	200	Frosted (Translucent)	
DX-TAP200	Packaging Substrates, Glass	UV	200	PO150	Acrylic 50	23000	200	Frosted (Translucent)	
DX-TAB165C	Packaging substrates	UV	165	EVA150	Acrylic 15	15000	140	Colorless (Transparent)	Prevents chipping, Easily peeled by hand
DX-TAB180C	Packaging substrates	UV	180	EVA150	Acrylic 30	12000	150	Blue (Translucent)	Prevents chipping, Good chip peeling by hand
DX-TAD80CN-R-X	Silicon Wafer	Non-UV	80	PVC70	Acrylic 10	1600	-	Colorless (Translucent)	Supports small chips
DX-PI 55	Silicon Wafer , SUS304	Non-UV	55	PI25	Acrylic30	1000	810	Blue (Translucent)	heat restiance at 150° for around 18 min
DX-TAP105-A	Silicon Wafer	Non-UV	105	PO90	Acrylic 15	6430		Blue (Translucent)	Acid-resistant Glacial acetic acid: water: nitric acid 2:20:40, the immersion time is 150 seconds

Back-Grinding and Bump Tape List

Item Name	Use	UV Type	Thickness (μm)	Base Material (μm)	Adhesive (μm)	Adhesive Strength (Before UV) mN/25mm	Adhesive Strength (After UV) mN/25mm	Color	Properties
DX-LCP175	BG standard compatible	UV	175	PO150	Acrylic 25	21000	200	Frosted (Translucent)	
DX-LCP180K	BG standard compatible	UV	180	PO150	Urethane 30	15000	180	Colorless (Transparent)	High tape thickness accuracy, easy to peel for thin film products (UV peeling)
DX-LCP130GX	BG standard compatible	UV	130	PO100	Urethane 30	13500	90	Colorless (Translucent)	Reasonably high tape thickness accuracy, relatively easy to peel for thin film products (UV peeling)
DX-LCP130GNX	BG standard compatible General purpose use	Non-UV	130	PO100	Acrylic 30	1200	-	Blue (Transparent)	
DX-LCP180LNX	BG standard compatible	Non-UV	180	PO150	Acrylic 30	1400	-	Blue (Transparent)	High tape thickness accuracy, Increased adhesive strength
DX-LCP200LNX	BG standard compatible	Non-UV	200	PO150	Acrylic 50	1900	-	Blue (Transparent)	High tape thickness accuracy, Increased adhesive strength
DX-LCP290Z	Bump Wafers	UV	290	PO150	Acrylic 140	22000	190	Colorless (Transparent)	

***New Development:* Tape Manufacturing Facility**

- In 2023, we launched a state-of-the-art tape manufacturing facility, marking a major step forward in our production capacity and global supply stability.
- The factory spans over 100,000 ft², purpose-built to support high-volume production while maintaining the flexibility required for custom tape solutions.
- This facility enables us to accelerate lead times, support growing demand, and strengthen our commitment to quality and innovation in semiconductor tape technology.



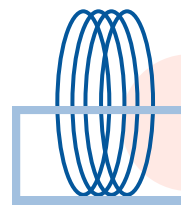
The site is fully equipped for:

- Product development and prototyping
- Coating and adhesive formulation
- Aging and curing processes
- Slitting and rewinding
- Precision measurement and inspection
- Final packaging and logistics

WAFERS

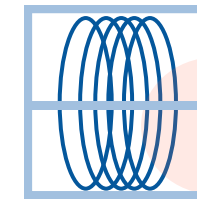
High-Quality Silicon Wafers for Every Application

D&X specializes in supplying wafers that can be tailored to satisfy any of your needs in the semiconductor sector. Proudly made in Japan, we uphold the highest standards of quality and service, ensuring our clients enjoy a reliable and professional partnership.



COINROLL WAFER

- 1-18 inch Available
- As-Sliced, Lapped, Ground, Etched and Polished



FINISHED MATERIAL

- 1-18 inch Available
- Test, Monitor, Prime Grade
- 14-300nm particle control



SILICON INGOT

- Diameter 53-310mm Available
- Orientation <100> <110> <111>

*For more details, please refer to our wafer list on the following pages.

OUR STRENGTHS

- **Extensive Inventory & Fast Delivery:** Immediate access to wafers from our ready-to-ship inventory, available from single cassettes to bulk orders over 10,000 units.
- **Low MOQ & Competitive Pricing:** Our streamlined operations and global logistics network enable us to offer affordable prices and accept small order quantities.
- **Diverse Product Formats for Vast Applications:** Available as ingots, 1-18 inch coinroll wafers, and finished material. Ideal for R&D, prototyping, and high-volume manufacturing.
- **Flexible Supply Scheduling:** Monthly, quarterly, and annual delivery options to support short-term and long-term projects.
- **Wide Range of Specifications:** Non-standard thickness (5 μ m-2000+ μ m), low to high resistivity (0.001-20,000ohm/cm), etc.



Wafer Specifications: 2"-8"

	2" Silicon Wafer	3" Silicon Wafer	4" Silicon Wafer	5" Silicon Wafer	6" Silicon Wafer	8" Silicon Wafer
Diameter	50.8±0.38 mm	76.2±0.63 mm	100±0.5 mm	125±0.5 mm	150±0.2 mm	200±0.2 mm
Type	P, N, Intrinsic	P, N, Intrinsic	P, N, Intrinsic	P, N, Intrinsic	P, N, Intrinsic	P, N, Intrinsic
Dopant	B, Ph, As, Sb, etc	B, Ph, As, Sb, etc	B, Ph, As, Sb, etc	B, Ph, As, Sb, etc	B, Ph, As, Sb, etc	B, Ph, As, Sb, etc
Orientation	<100>, <110>, <111>	<100>, <110>, <111>	<100>, <110>, <111>	<100>, <110>, <111>	<100>, <110>, <111>	<100>, <110>, <111>
Thickness	279±25 µm	381±25 µm	525±25 µm	625±25 µm	625±25/ 675±25 µm	725±25 µm
Flat/Notch	SEMI flat	1 or 2 SEMI flat	1 or 2 SEMI flat	SEMI flat	SEMI / JEITA flat, notch	SEMI notch, flat
TTV	<10 µm	<10 µm	<10 µm	<10 µm	<10 µm	<10 µm
Bow/Warp	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm
Surface Finish	SSP, DSP, DSE, As-cut, etc.	SSP, DSP, DSE, As-cut, etc.	SSP, DSP, DSE, As-cut, etc.	SSP, DSP, DSE, As-cut, etc.	SSP, DSP, DSE, As-cut, etc.	SSP, DSP, DSE, As-cut, etc.
Particles	<20@0.3 µm	<20@0.3 µm	<20@0.3 µm	<20@0.3 µm	<20@0.3 µm/ <50@0.2 µm	<50@0.2 µm

Customized Specifications Available

Wafer Specifications: 12"

	12" Silicon Wafer	12" Silicon Wafer	12" Silicon Wafer	12" Silicon Wafer	12" Silicon Wafer	12" Silicon Wafer
Diameter	300±0.2 mm	300±0.2 mm	300±0.2 mm	300±0.2 mm	300±0.2 mm	300±0.2 mm
Type	P, N, Intrinsic	P, N	P, N	P, N	P, N	P, N
Orientation	<100>	<100>	<100>	<100>	<100>	<100>
Thickness	775±25 µm	775±25 µm	775±25 µm	775±25 µm	775±25 µm	775±25 µm
Notch	SEMI notch	SEMI notch	SEMI notch	SEMI notch	SEMI notch	SEMI notch
TTV	<10 µm	<10 µm	<5 µm	<5 µm	<2 µm	<2 µm
Bow/Warp	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm	<40 µm/<40 µm
Surface Finish	DSP	DSP	DSP	DSP	DSP	DSP
Particles	<50@0.2 µm	<50@0.09 µm	<50@0.065 µm	<50@0.045 µm	<50@0.026 µm	<50@0.019 µm

Customized Specifications Available

BEYOND SILICON

Specialized Wafers for Advanced Applications

SiC

Sapphire

Quartz

Glass

SOI

Bonded Wafer

Thermocouple Wafer

Epi Wafers

Others

Metal Films

Al

Ni

Ti

Cu

TiN

Etc.

Insulating Films

SiO₂

Si₃N₄

PE-TEOS

III-V Coumpounds

GaAs

GaN

InP



ACCESSORIES

Complete Support with High-Quality Accessories



Wafer Cassettes

We supply a wide range of wafer cassettes designed for safe storage and transport within cleanroom environments:

- FOSB (Front Opening Shipping Box)
- FOUP (Front Opening Unified Pod)
- Flat Cases such as Protos, Jar Cases, and more



Wafer Rings

We offer high-quality wafer rings in sizes ranging from 6" to 12", compatible with a variety of semiconductor processing tools. Our rings ensure secure handling and stable mounting during dicing, back-grinding, and other critical production steps.



SERVICES

From Raw Substrate to Production-Ready Wafers

Thinning

Dicing

Polishing

Bonding

Cleaning & Packaging

Bumping

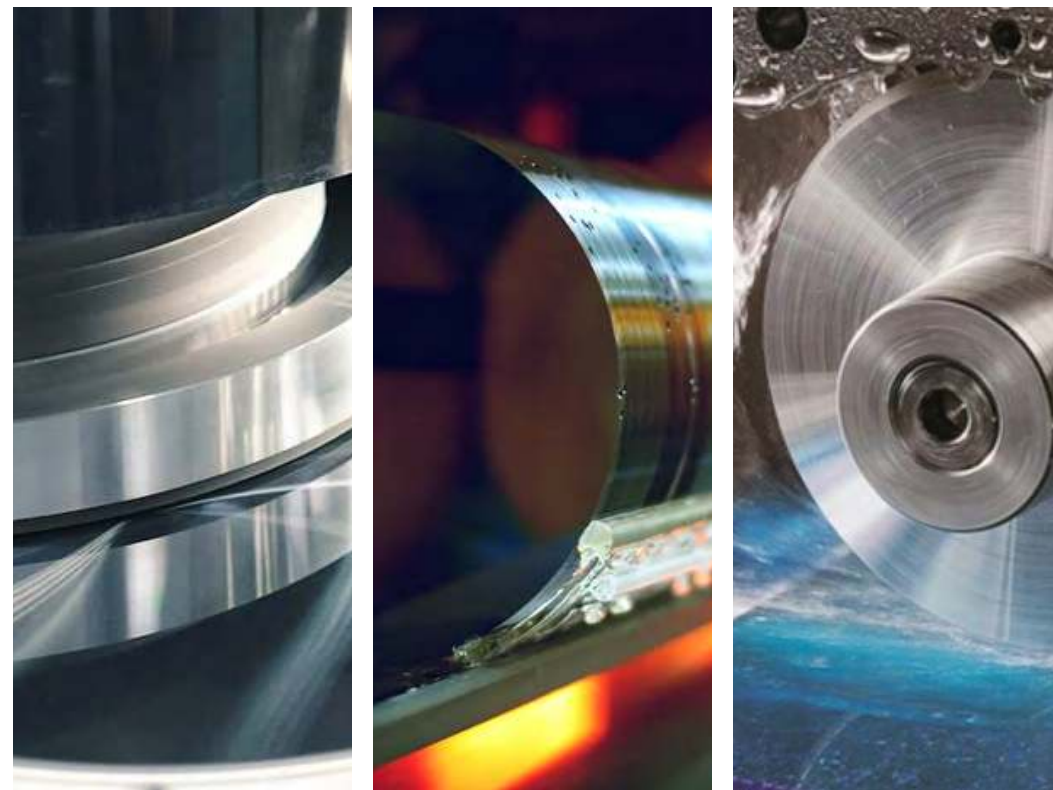
Metrology & Inspection

Films

Pattern

Lithography

Laser Marking



We provide a comprehensive range of wafer processing services, including thinning, dicing, polishing, coating, and more. With a strong focus on precision and efficiency, we tailor each process to meet the exact demands of your semiconductor projects.





ISO 9001:2015 Certified



This is to certify that the management system of:

D&X Co., Ltd.

Main Site: 1-1-4 Nagaoka, Mizuhomachi, Nishitama-Gun, Tokyo, Japan
has been registered by Intertek as conforming to the requirements of:

ISO 9001:2015

The management system is applicable to:

Processing and sales of semiconductor wafers and manufacture and sales of consumables such as various semiconductor related tapes

Certificate Number:
14038

Initial Certification Date:
17 November 2020

Date of Certification Decision:
05 October 2023

Issuing Date:
05 October 2023

Valid Until:
16 November 2026



Calin Moldovean
President, Business Assurance

Intertek Certification Limited, 10A Victory Park,
Victory Road, Derby DE24 8ZF, United Kingdom

Intertek Certification Limited is a UKAS
accredited body under schedule of
accreditation no. 014.

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Your Partner in Semiconductor Innovation

Headquarter:

D&X Co., Ltd.
1-1-4 Nagaoka, Mizuho
Nishitama-Gun, 190-1232
Tokyo, Japan

Phone: [+81 42 557 2227](tel:+81425572227)
Fax: [+81 42 557 2227](tel:+81425572227)
E-Mail: sales@dong-xu.co.jp

Website: www.dong-xu.co.jp/en/

Germany Office:

D&X GmbH
Kasteelstraße 9
47199 Duisburg
Germany

Taiwan Office:

D&X (Taiwan) Co.,
Ltd
4 F.-6, No. 2,
Fuxing N. Rd.,
Zhongshan Dist.,
Taipei City 104100,
Taiwan (R.O.C)

China Office:

Shanghai Dongxu Electronic
Technology Co, Ltd.,
Shanghai Waigaogiao,
Pilot Free Trade Zone,
Shanghai 200131, China



*Contact us today for a customized quote!
Our team responds to all inquiries within 24 hours.*